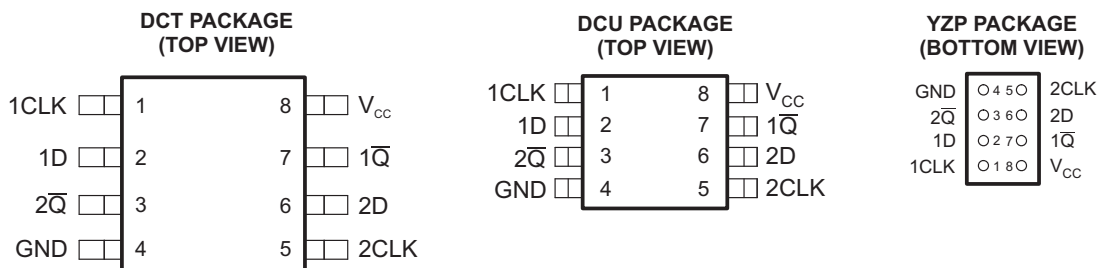


FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max t_{pd} of 1.9 ns at 1.8 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 8 -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This dual positive-edge-triggered D-type flip-flop is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

When data at the data (D) input meets the setup time requirement, the data is transferred to the $\bar{Q}$ output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
–40°C to 85°C	NanoFree™ – WCSP (DSBGA)	Reel of 3000	SN74AUC2G80YZPR	__ _UX_
	0.23-mm Large Bump – YZP (Pb-free)			
	SSOP – DCT	Reel of 3000	SN74AUC2G80DCTR	U80__ _
	VSSOP – DCU	Reel of 3000	SN74AUC2G80DCUR	UX_

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.

DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

SN74AUC2G80

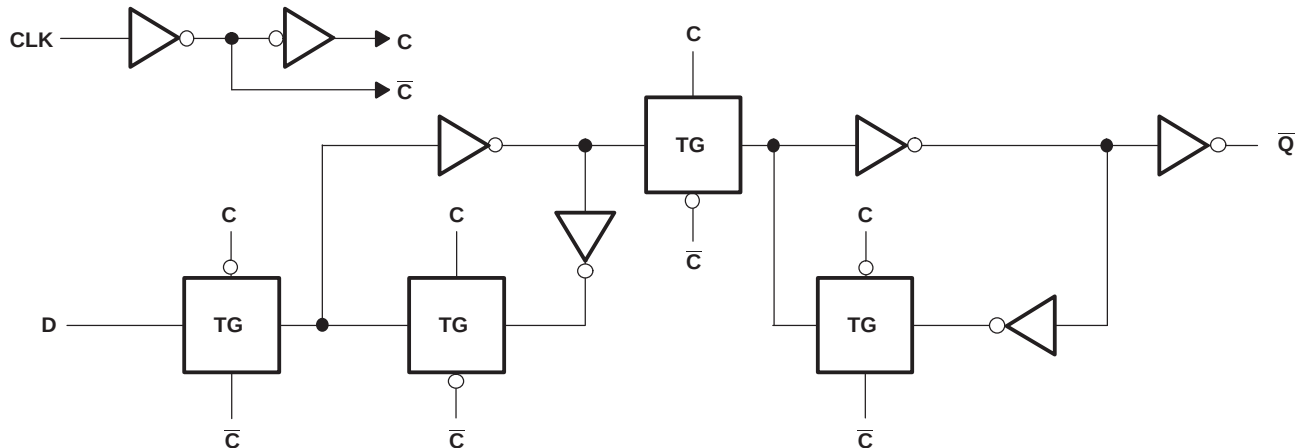
DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP

SCES540C – JANUARY 2004 – REVISED JANUARY 2007

**FUNCTION TABLE
(EACH FLIP-FLOP)**

INPUTS		OUTPUT Q
CLK	D	
↑	H	L
↑	L	H
L	X	Q ₀

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		−0.5	3.6	V
V _I	Input voltage range ⁽²⁾		−0.5	3.6	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾		−0.5	3.6	V
V _O	Output voltage range ⁽²⁾		−0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0	−50		mA
I _{OK}	Output clamp current	V _O < 0	−50		mA
I _O	Continuous output current		±20		mA
Continuous current through V _{CC} or GND			±100		mA
θ _{JA}	Package thermal impedance ⁽³⁾	DCT package	220		°C/W
		DCU package	227		
		YZP package	102		
T _{std}	Storage temperature range		−65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		0.8	2.7	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}		V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	1.7		
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V		0	V
		V _{CC} = 1.1 V to 1.95 V		0.35 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V		0.7	
V _I	Input voltage		0	3.6	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 0.8 V		–0.7	mA
		V _{CC} = 1.1 V		–3	
		V _{CC} = 1.4 V		–5	
		V _{CC} = 1.65 V		–8	
		V _{CC} = 2.3 V		–9	
I _{OL}	Low-level output current	V _{CC} = 0.8 V		0.7	mA
		V _{CC} = 1.1 V		3	
		V _{CC} = 1.4 V		5	
		V _{CC} = 1.65 V		8	
		V _{CC} = 2.3 V		9	
Δt/Δv	Input transition rise or fall rate			20	ns/V
T _A	Operating free-air temperature		–40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}		I _{OH} = –100 μA	0.8 V to 2.7 V	V _{CC} – 0.1			V
		I _{OH} = –0.7 mA	0.8 V		0.55		
		I _{OH} = –3 mA	1.1 V		0.8		
		I _{OH} = –5 mA	1.4 V		1		
		I _{OH} = –8 mA	1.65 V		1.2		
		I _{OH} = –9 mA	2.3 V		1.8		
V _{OL}		I _{OL} = 100 μA	0.8 V to 2.7 V			0.2	V
		I _{OL} = 0.7 mA	0.8 V		0.25		
		I _{OL} = 3 mA	1.1 V			0.3	
		I _{OL} = 5 mA	1.4 V			0.4	
		I _{OL} = 8 mA	1.65 V			0.45	
		I _{OL} = 9 mA	2.3 V			0.6	
I _I	D or CLK inputs	V _I = V _{CC} or GND	0 to 2.7 V			±5	μA
I _{off}		V _I or V _O = 2.7 V	0			±5	μA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	0.8 V to 2.7 V			10	μA
C _i		V _I = V _{CC} or GND	2.5 V		2.5		pF

(1) All typical values are at T_A = 25°C.

SN74AUC2G80

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP

SCES540C – JANUARY 2004 – REVISED JANUARY 2007

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

		$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V} \pm 0.1\text{ V}$		$V_{CC} = 1.5\text{ V} \pm 0.1\text{ V}$		$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		UNIT
		TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	50	200		225		250		275		MHz
t_w	Pulse duration, CLK high or low	2.4	1		1		1		1		ns
t_{su}	Setup time before CLK $\uparrow$	1	0.8		0.6		0.6		0.5		ns
t_h	Hold time, data after CLK $\uparrow$	0	0		0.1		0.1		0.5		ns

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 15\text{ pF}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = 1.2 V ± 0.1 V		V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			50	200		225		250			275		MHz
t _{pd}	CLK	$\overline{Q}$	5	1	3.9	0.8	2.5	0.3	1	1.9	0.3	1.3	ns

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30\text{ pF}$ (unless otherwise noted) (see [Figure 1](#))

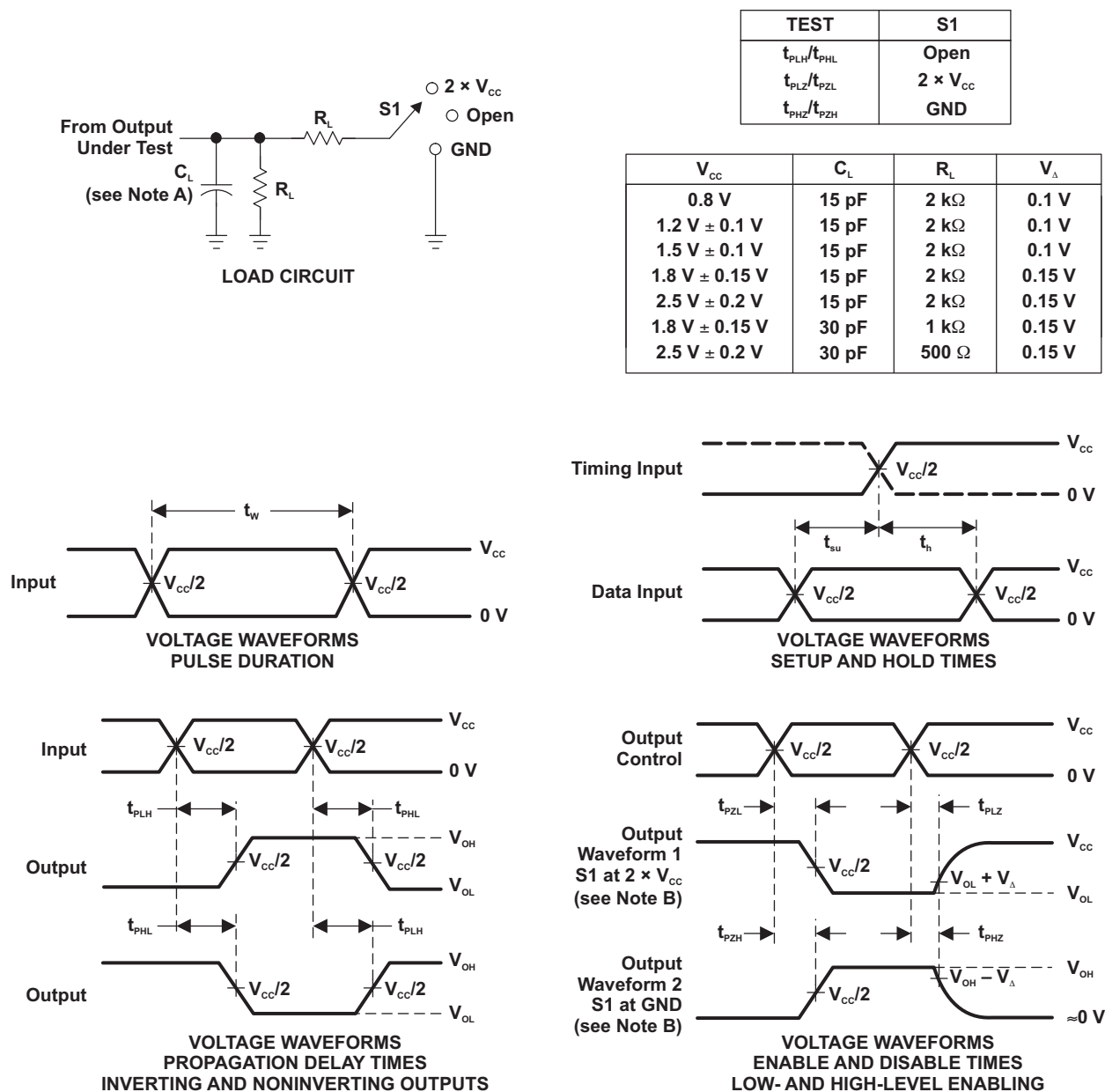
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$			$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
f_{max}			250			275		ns
t_{pd}	CLK	$\overline{Q}$	0.8	1.5	2.4	0.6	1.8	ns

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V}$	$V_{CC} = 1.5\text{ V}$	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	UNIT
			TYP	TYP	TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Data	16.9	17.2	18.6	21.4	29.5	pF
		CLK	1.1	1.1	1.2	1.4	2.5	
		Total	18	18.3	19.8	22.8	32	

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz, $Z_o = 50 \Omega$, slew rate $\geq$ 1 V/ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74AUC2G80DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U80 Z	Samples
SN74AUC2G80DCTRE4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U80 Z	Samples
SN74AUC2G80DCTRG4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U80 Z	Samples
SN74AUC2G80DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U80R	Samples
SN74AUC2G80DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U80R	Samples
SN74AUC2G80DCURG4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	U80R	Samples
SN74AUC2G80YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	UX7	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

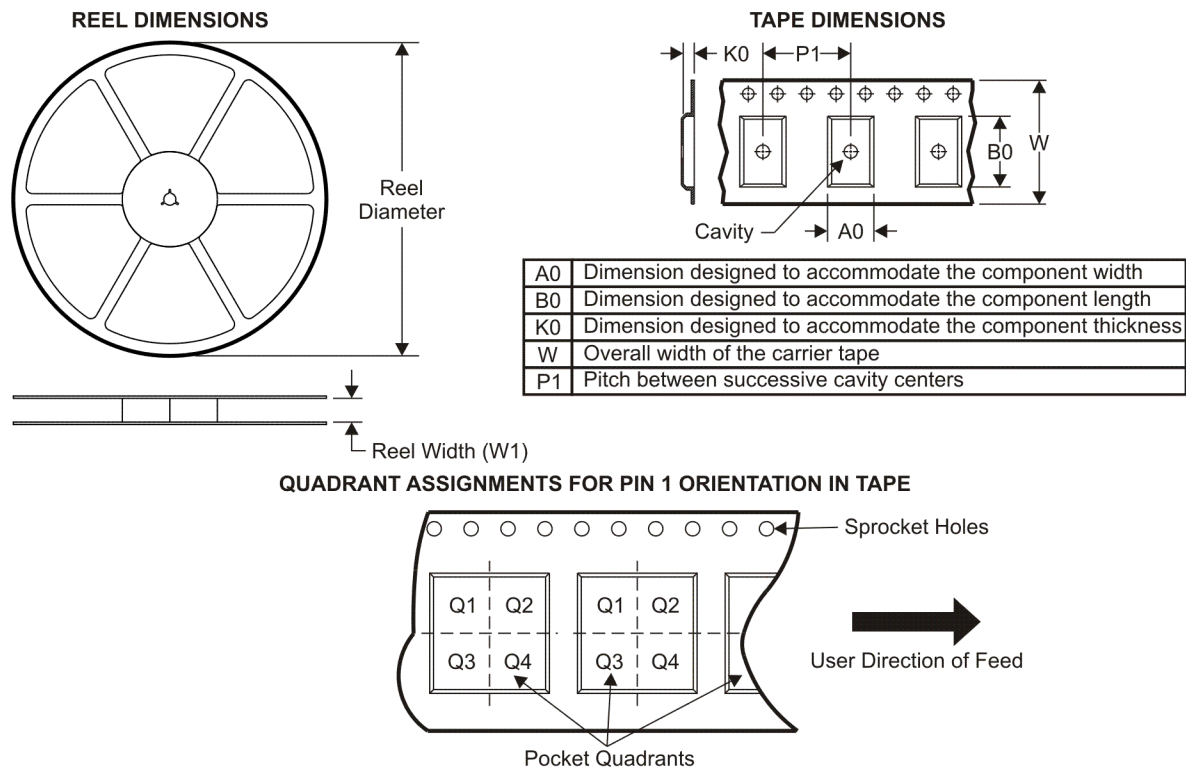
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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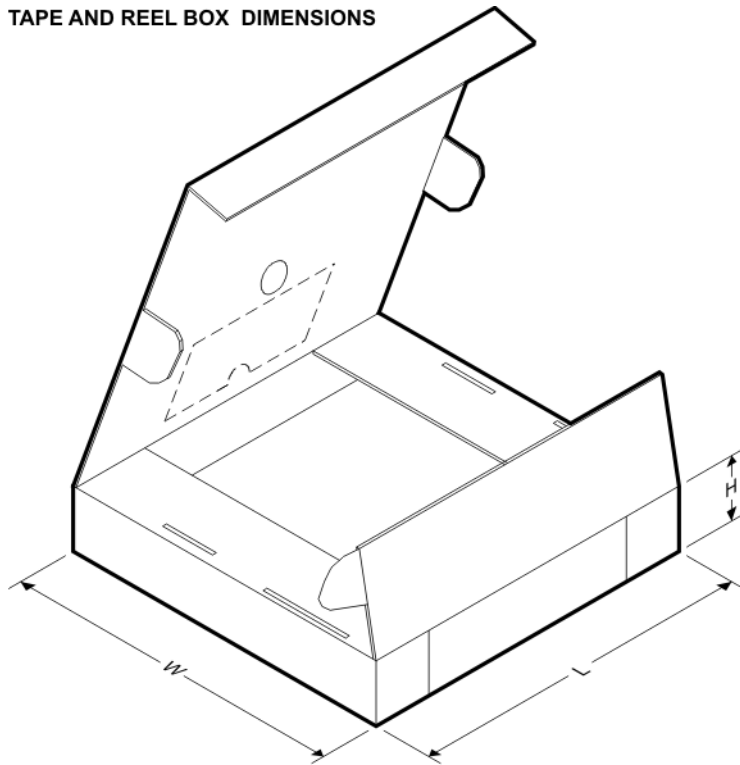
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUC2G80DCUR	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUC2G80YZPR	DSBGA	YZP	8	3000	180.0	8.4	1.02	2.02	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS

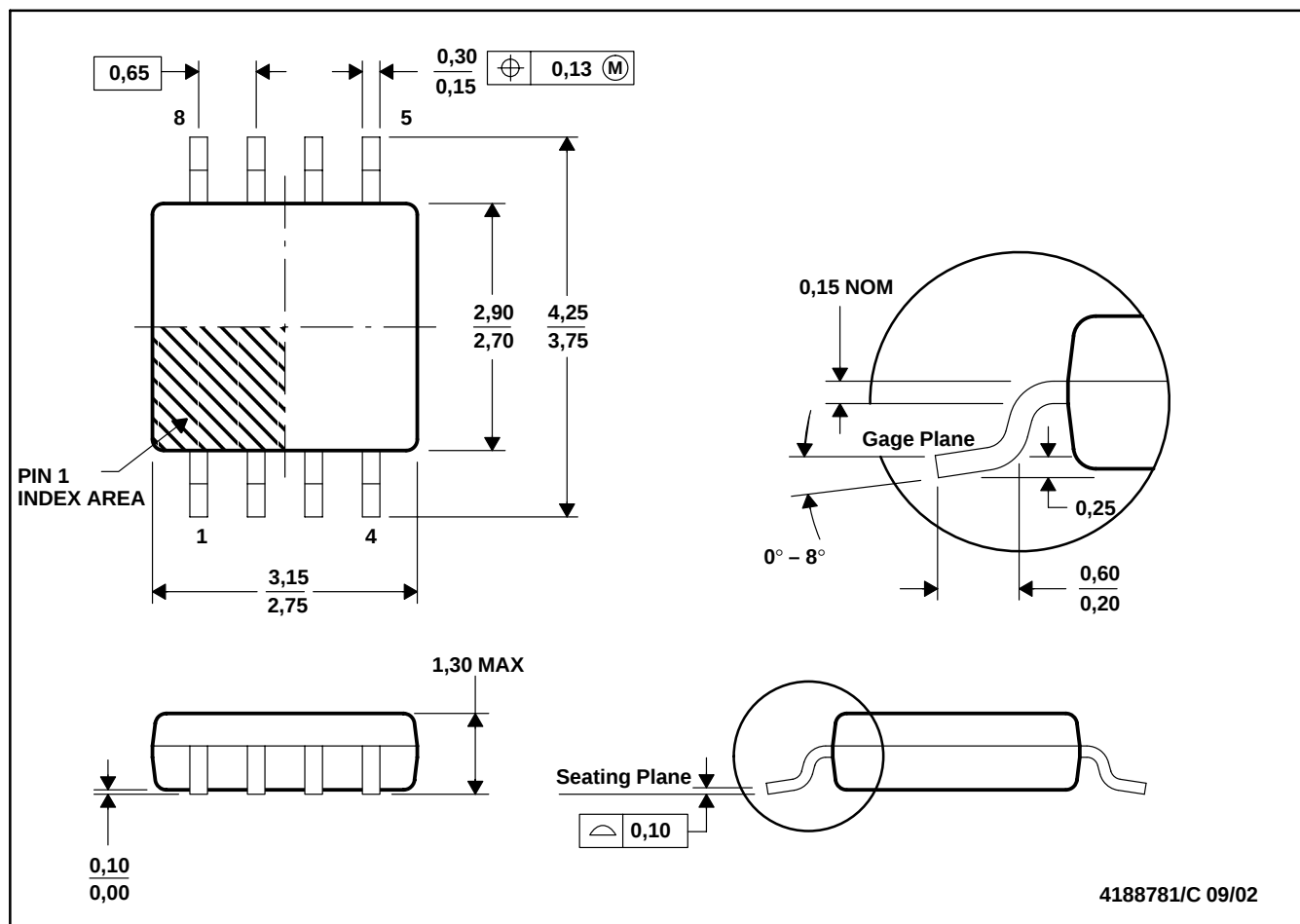


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUC2G80DCUR	US8	DCU	8	3000	202.0	201.0	28.0
SN74AUC2G80YZPR	DSBGA	YZP	8	3000	220.0	220.0	34.0

DCT (R-PDSO-G8)

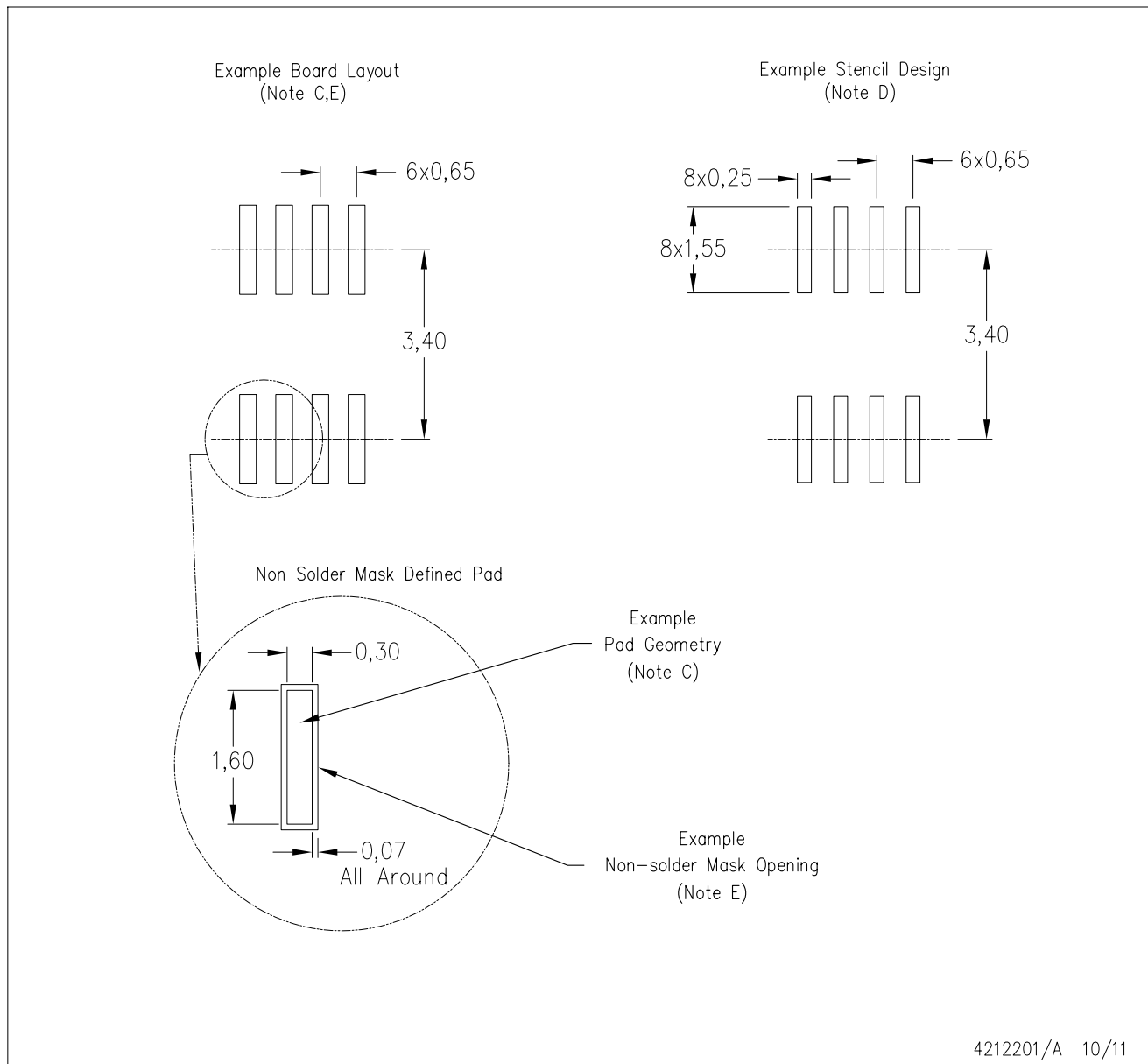
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - Falls within JEDEC MO-187 variation DA.

DCT (R-PDSO-G8)

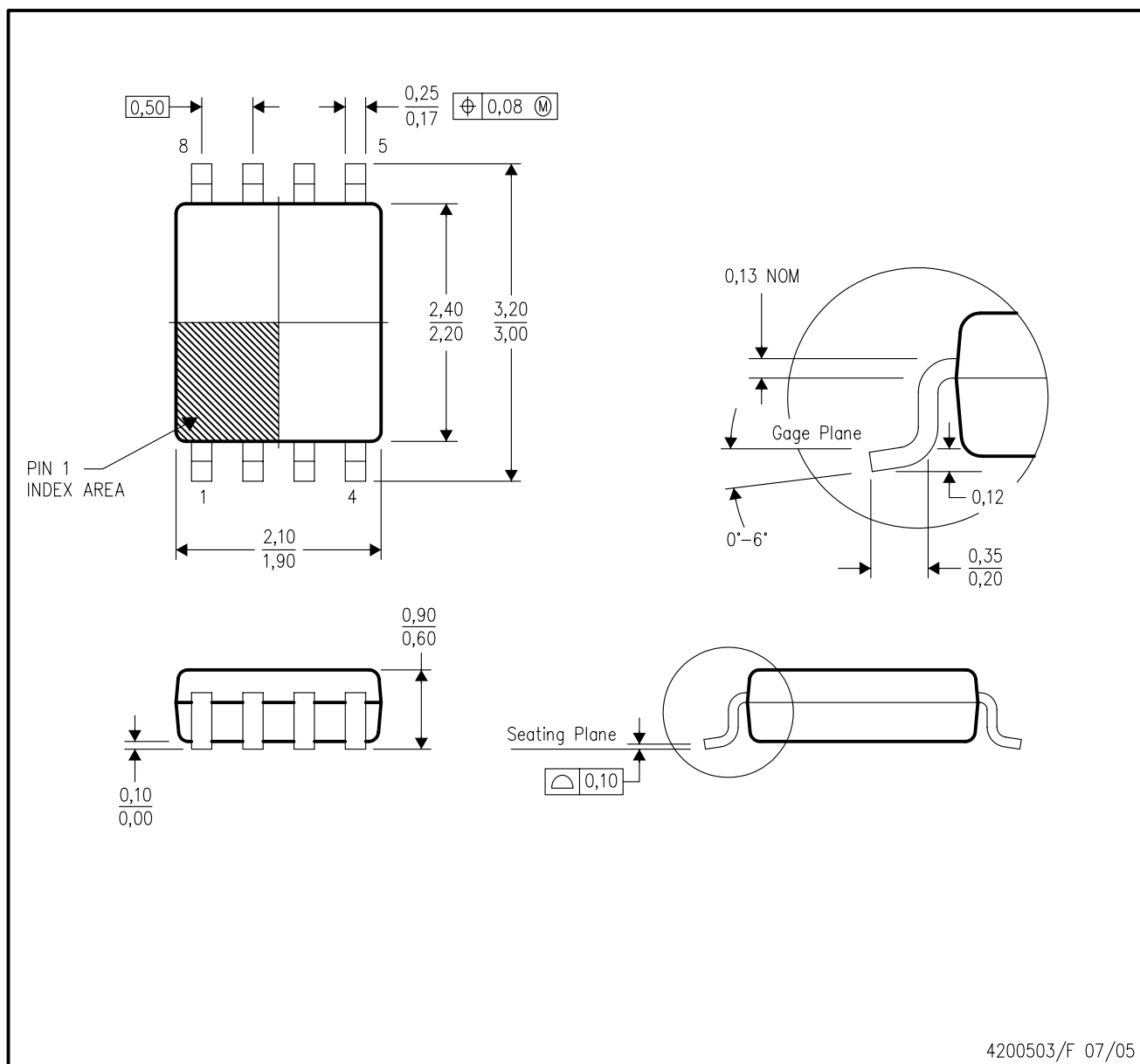
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DCU (R-PDSO-G8)

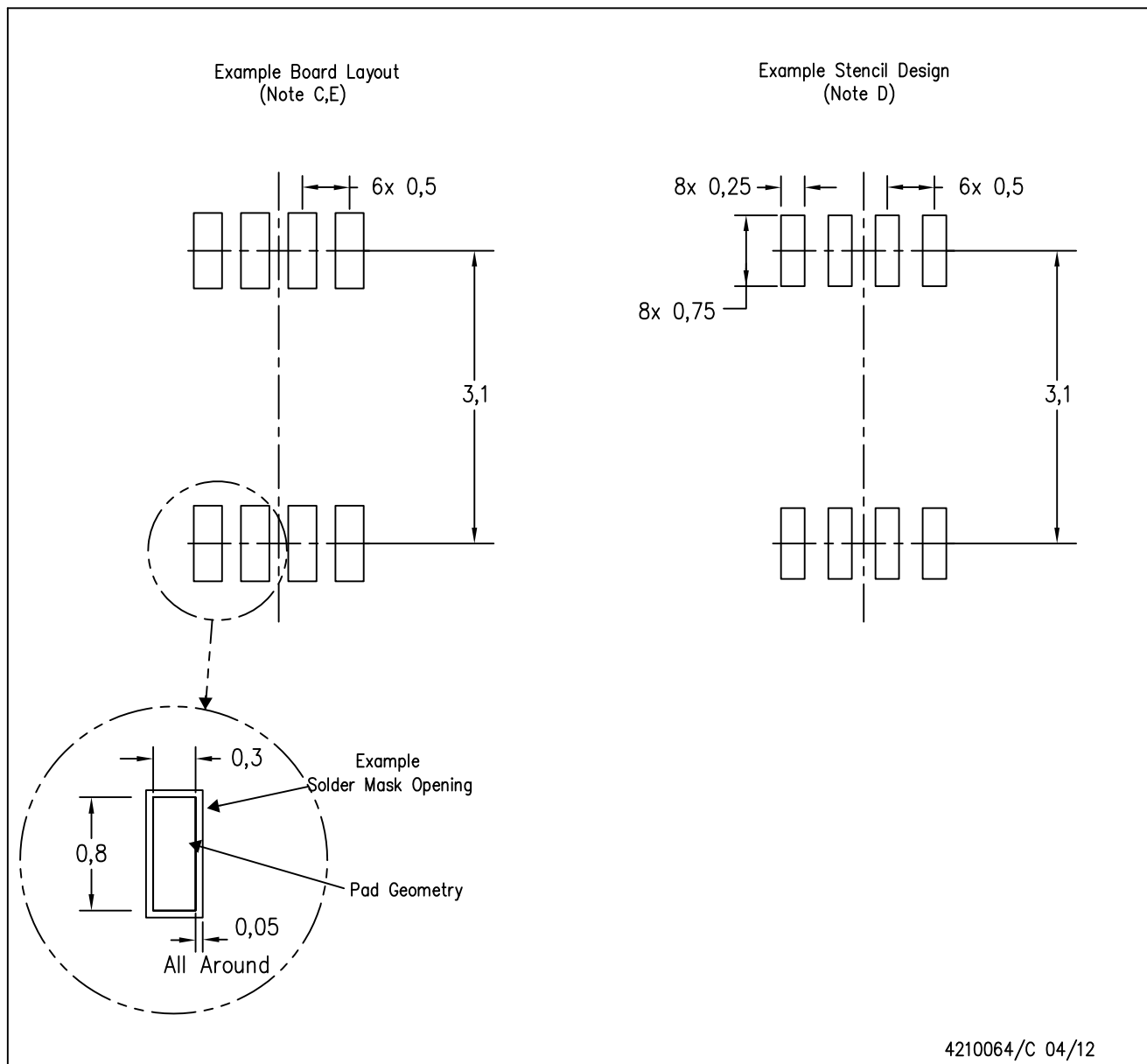
PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-187 variation CA.

DCU (S-PDSO-G8)

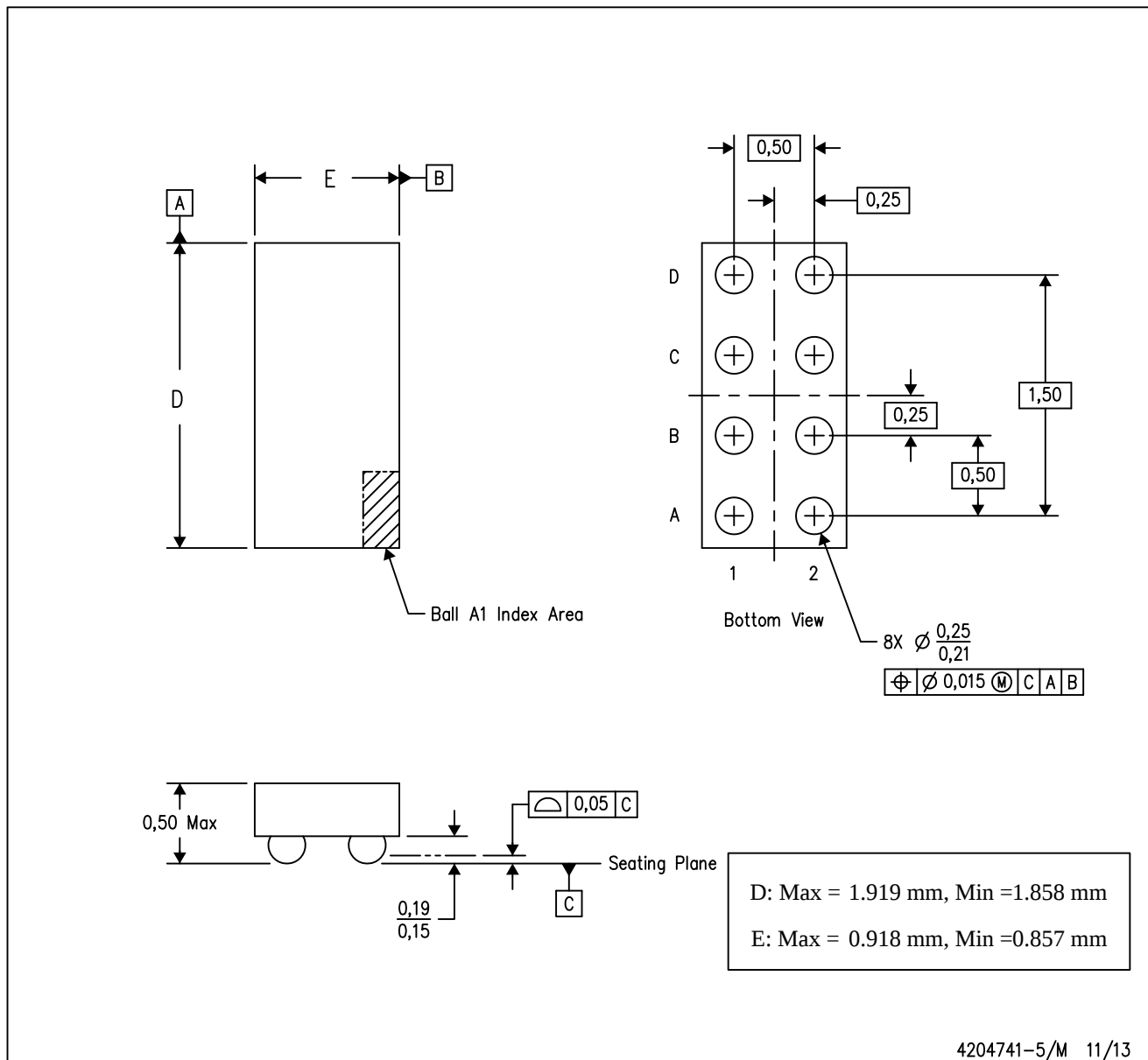
PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

YZP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

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